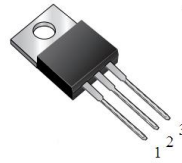
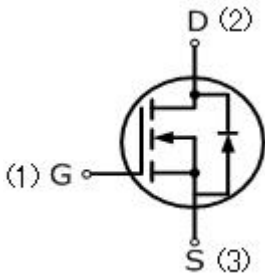


## 2N60(F,B,H,G,D)

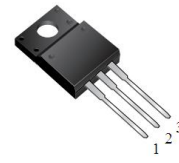
### 2A mps,600 Volts N-CHANNEL MOSFET

#### FEATURE

- 2A,600V, $R_{DS(ON)}=4\Omega$  @ $V_{GS}=10V/1A$
- Low gate charge
- Low  $C_{iss}$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



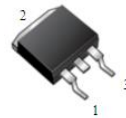
TO-220AB  
2N60



ITO-220AB  
2N60F



TO-262  
2N60H



TO-263  
2N60B



TO-252  
2N60G



TO-251  
2N60D

#### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	2N60	UNIT
Drain-Source Voltage	$V_{DSS}$	600	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	
Continuous Drain Current	$I_D$	2	A
Pulsed Drain Current(Note1)	$I_{DM}$	8	
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	120	mJ
Avalanche Current(Note1)	$I_{AR}$	2.0	A
Repetitive Avalanche Energy (Note1)	$E_{AR}$	5.4	mJ
Reverse Diode dV/dt (Note 3)	dV/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	$T_L$	260	$^\circ\text{C}$
Mounting Torque	6-32 or M3 screw	10	lbf • in
		1.1	N • m

#### Thermal Characteristics

Parameter	Symbol	ITO-220	TO-220	TO-262 TO-263	TO-251 TO-252	Units
Maximum Junction-to-Case	$R_{thJC}$	4	2	2	6	$^\circ\text{C}/\text{W}$
Maximum Power Dissipation	$P_D$	32	62	62	21	W

<b>Electrical Characteristics</b> ( $T_c=25^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	600	—	—	V
Breakdown Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=250\mu A$	—	0.5	—	$V/^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=600V, V_{GS}=0V$	—	—	1	$\mu A$
Gate-Body Leakage Current, Forward	$I_{GSSF}$	$V_{GS}=30V, V_{DS}=0V$	—	—	100	nA
Gate-Body Leakage Current, Reverse	$I_{GSSR}$	$V_{GS}=-30V, V_{DS}=0V$	—	—	-100	nA
<b>On Characteristics</b>						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	—	4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=1A$	—	—	4	$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0\text{MHz}$	—	180	235	pF
Output Capacitance	$C_{oss}$		—	20	25	pF
Reverse Transfer Capacitance	$C_{rss}$		—	4.3	5.6	pF
<b>Switching Characteristics</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=300V, I_D=2A,$ $R_G=25\Omega$ (Note4,5)	—	9	28	ns
Turn-On Rise Time	$t_r$		—	25	60	ns
Turn-Off Delay Time	$t_{d(off)}$		—	24	58	ns
Turn-Off Fall Time	$t_f$		—	28	66	ns
Total Gate Charge	$Q_g$	$V_{DS}=480V, I_D=2A,$ $V_{GS}=10V,$ (Note4,5)	—	8.5	12	nC
Gate-Source Charge	$Q_{gs}$		—	1.3	—	nC
Gate-Drain Charge	$Q_{gd}$		—	4.1	—	nC
<b>Drain-Source Body Diode Characteristics and Maximum Ratings</b>						
Continuous Diode Forward Current	$I_S$		—	—	2	A
Pulsed Diode Forward Current	$I_{SM}$		—	—	8	A
Diode Forward Voltage	$V_{SD}$	$I_S=2A, V_{GS}=0V$	—	—	1.4	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=2A,$	—	230	—	ns
Reverse Recovery Charge	$Q_{rr}$	$dI_F/dt=100A/\mu s,$ (Note4)	—	1	—	$\mu C$

#### Notes

1. Repetitive Rating: pulse width limited by maximum junction temperature
2.  $V_{DD}=50V$ , starting,  $L=58\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=2A$ ,  $T_J=25^\circ\text{C}$
3.  $I_{SD} \leq I_D$ ,  $dI/dt=200A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ , starting  $T_J=25^\circ\text{C}$ .
4. Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .
5. Repetitive rating; pulse width limited by maximum junction temperature.